

FIG. 1(a)

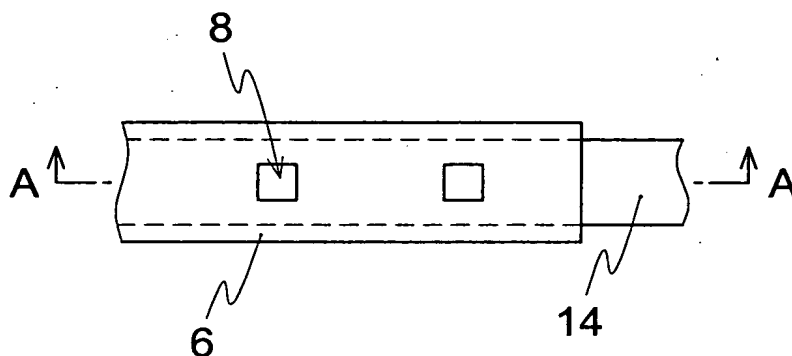


FIG. 1(b)

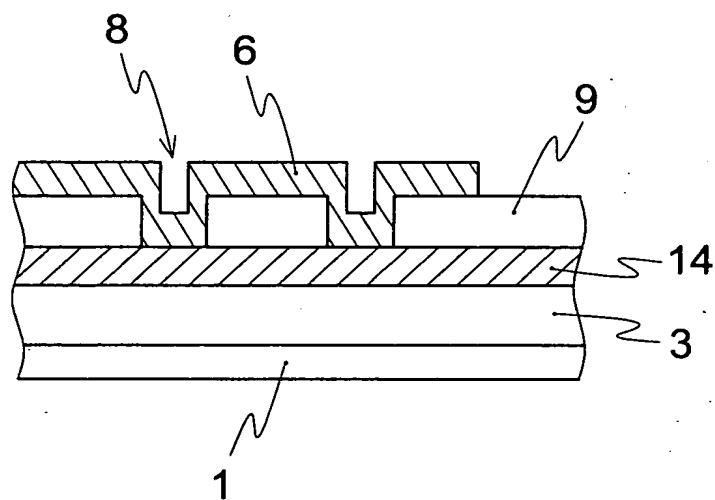


FIG. 2(a)

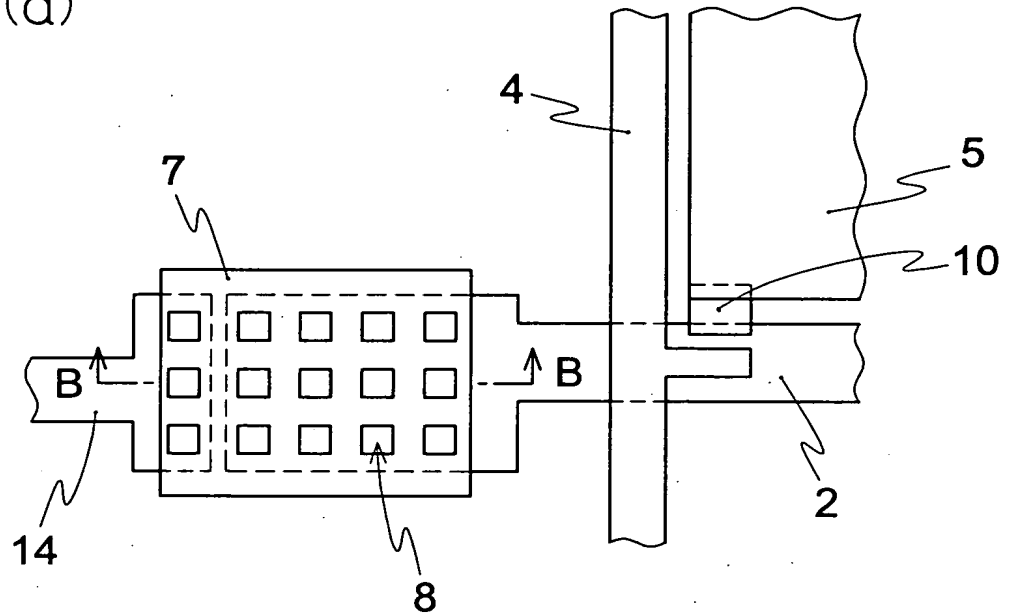


FIG. 2(b)

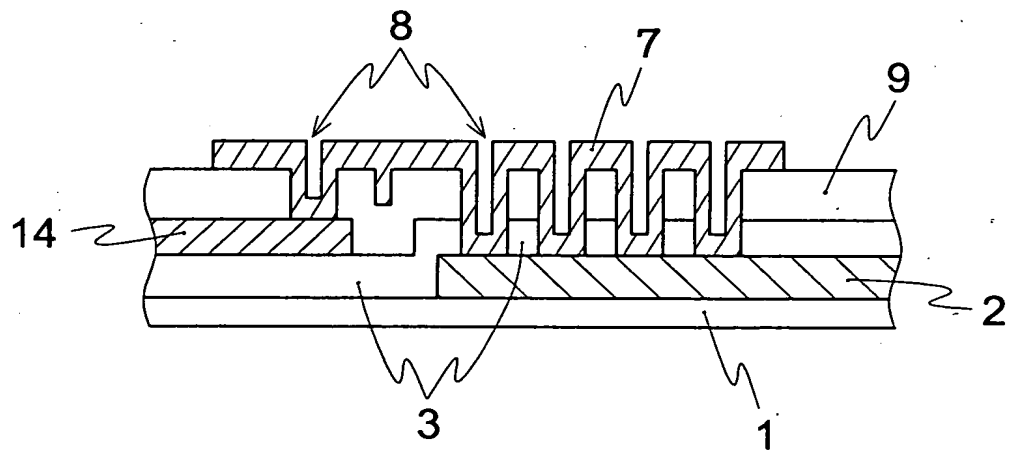


FIG. 3(a)

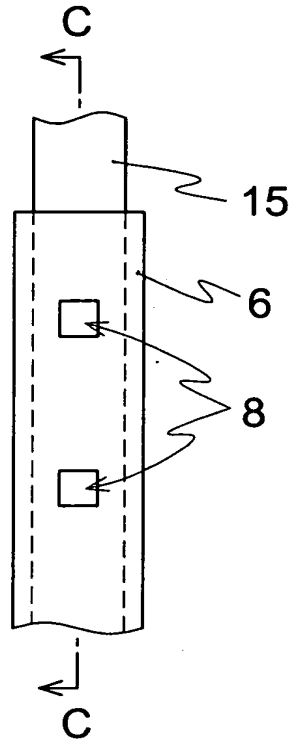
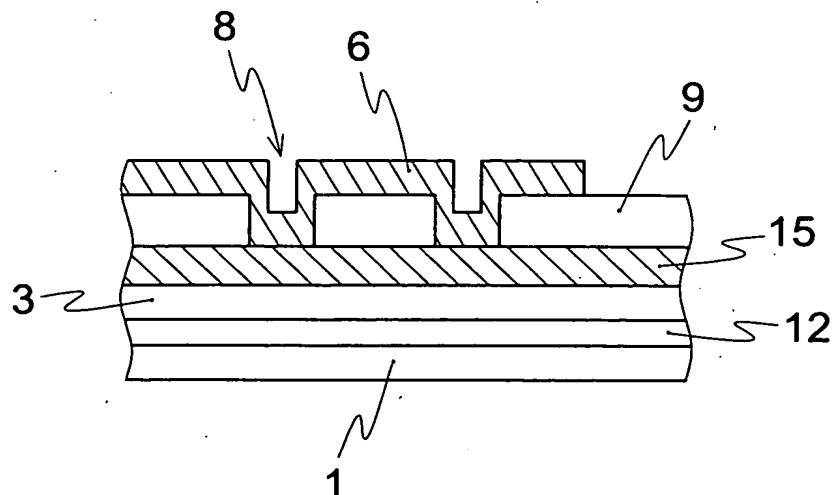


FIG. 3(b)



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FIG. 4(a)

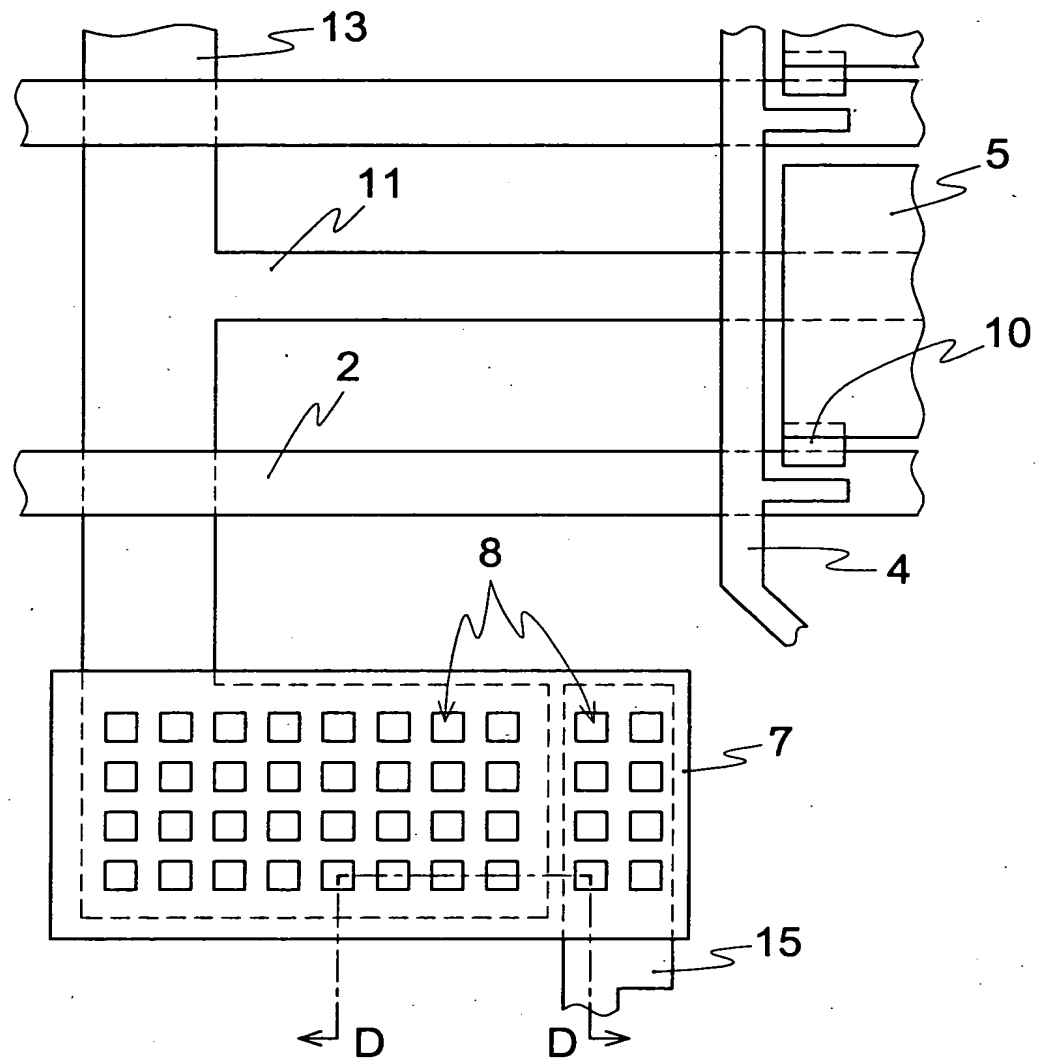


FIG. 4(b)

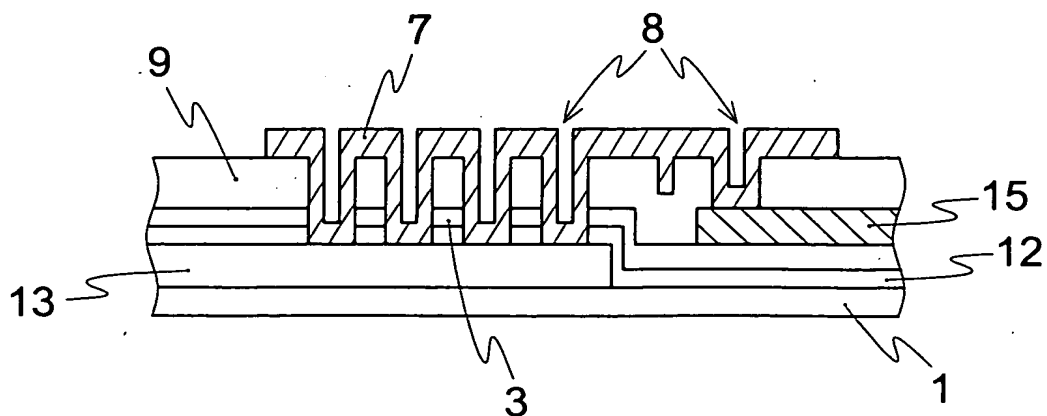


FIG. 5(a)

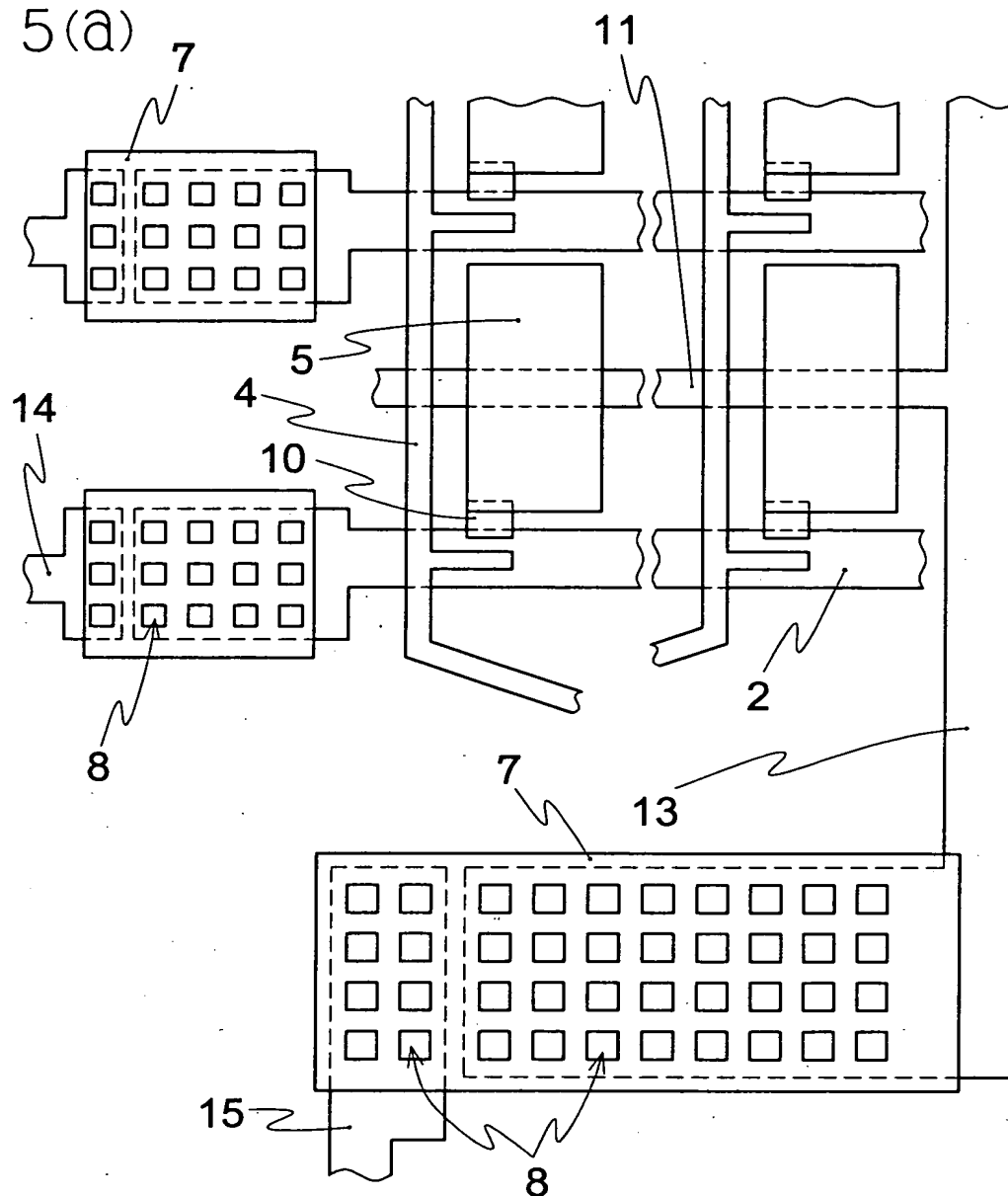


FIG. 5(b)

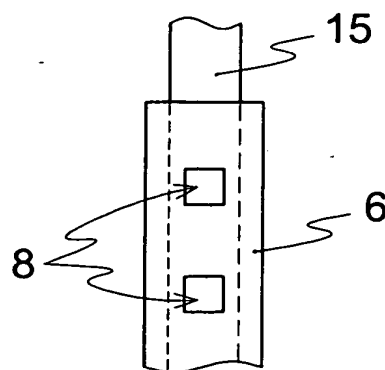


FIG. 6(a)

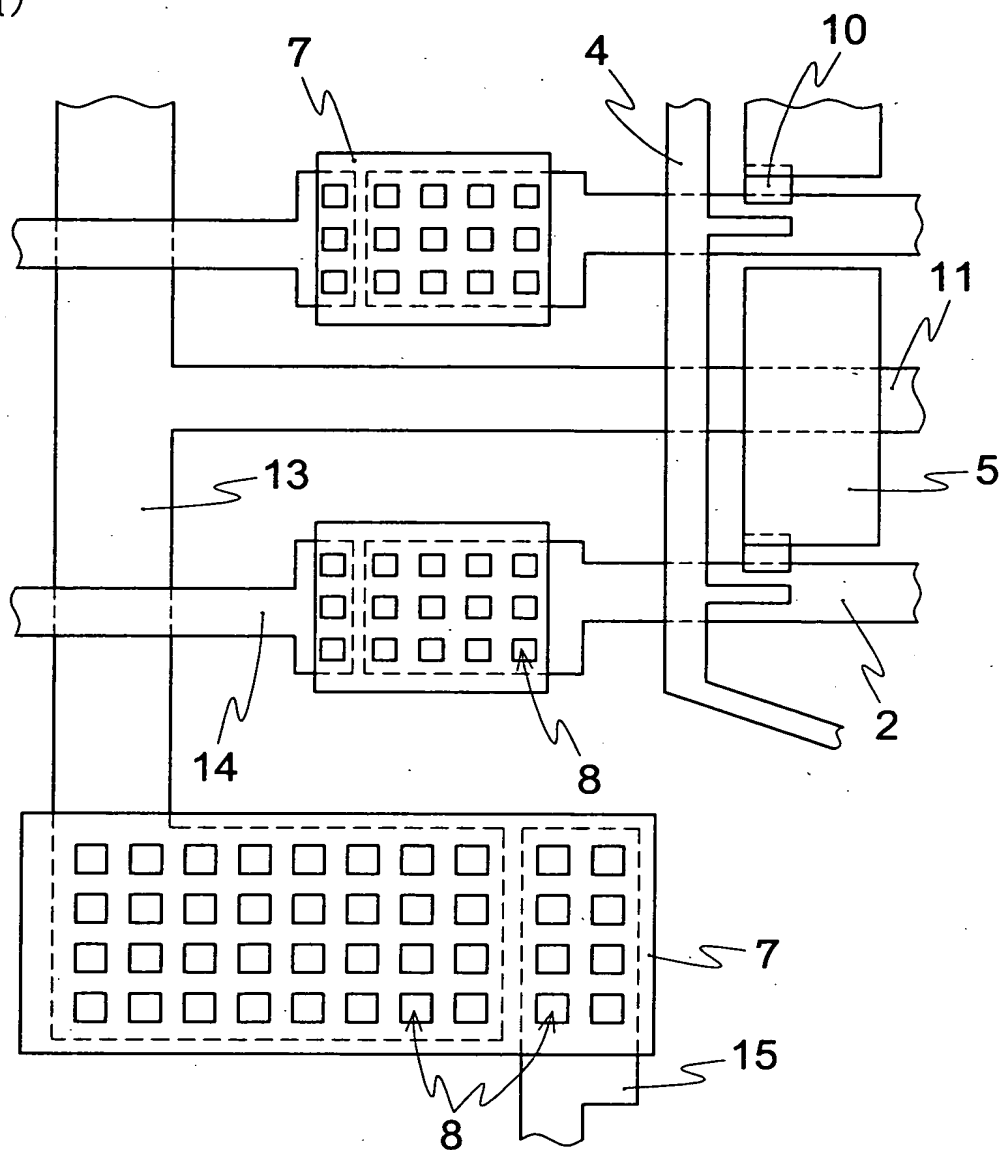


FIG. 6(b)

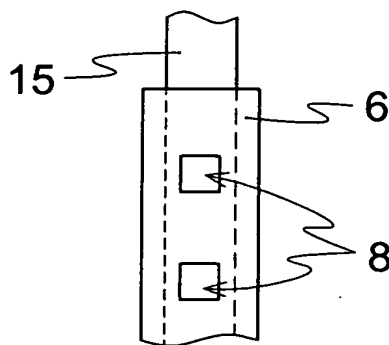


FIG. 7(a)

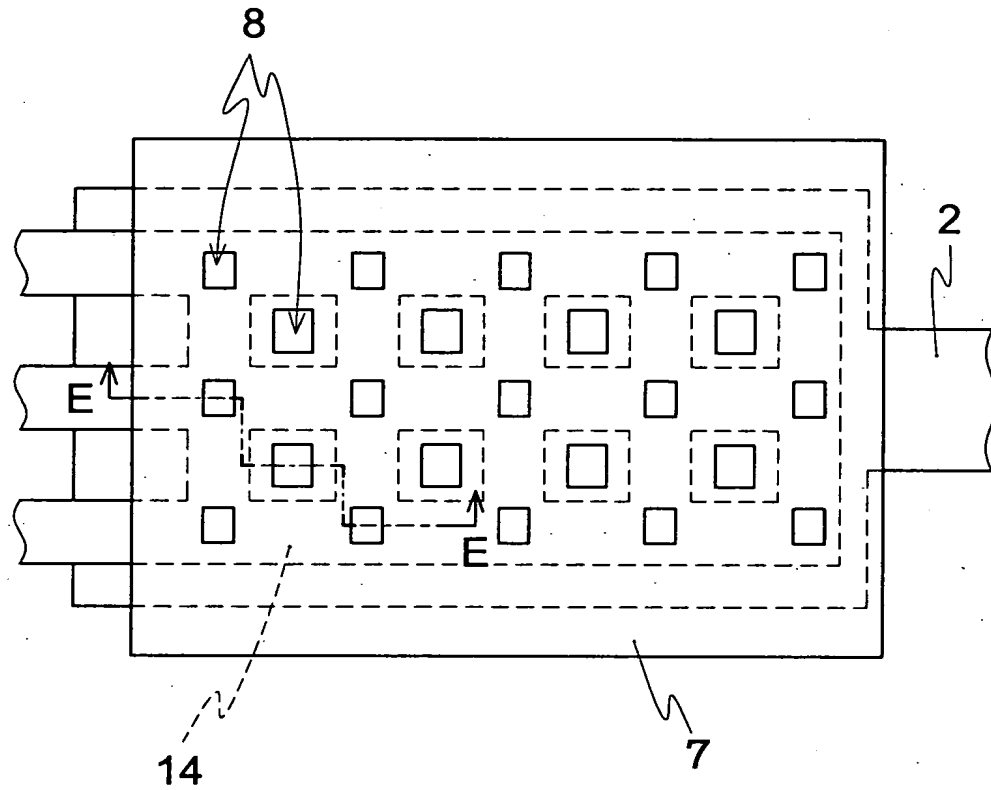


FIG. 7(b)

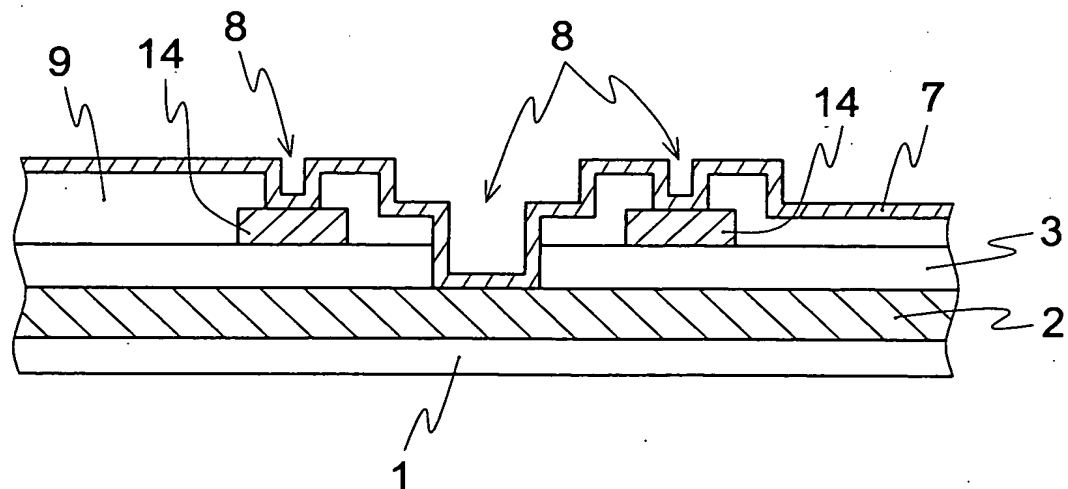


FIG. 8(a)

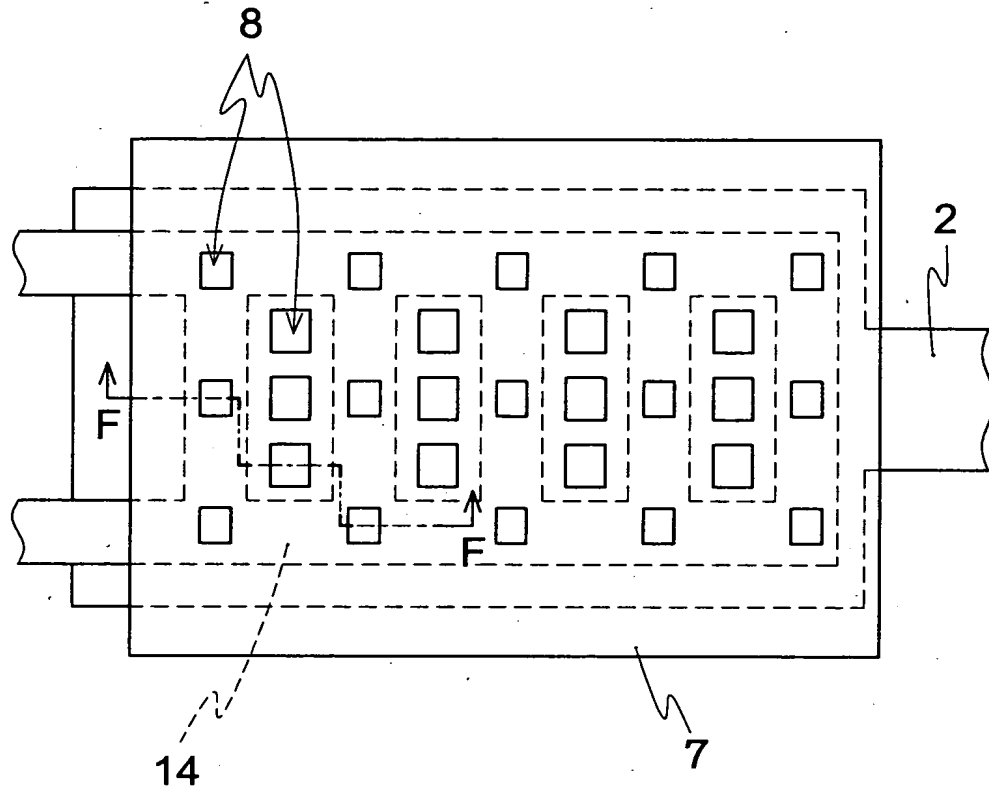


FIG. 8(b)

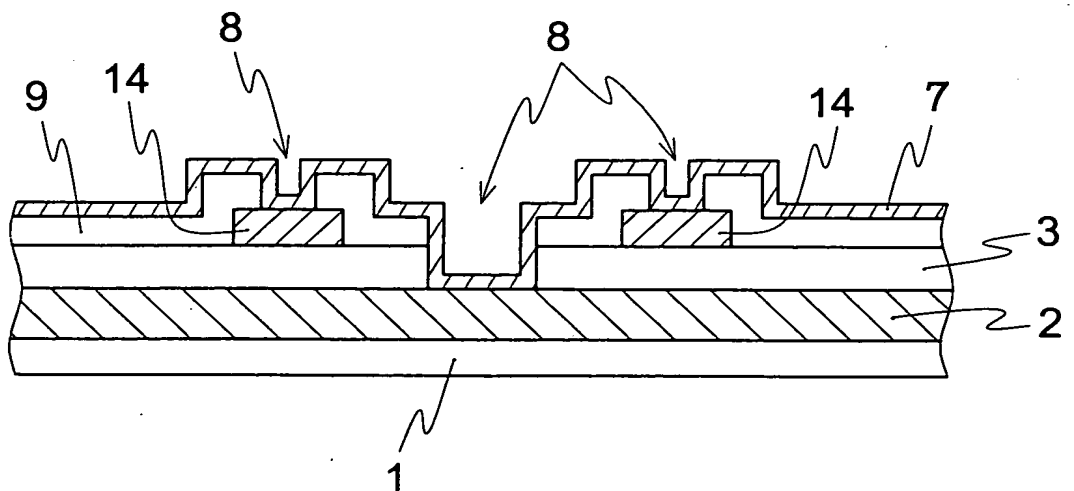




FIG. 9(a)

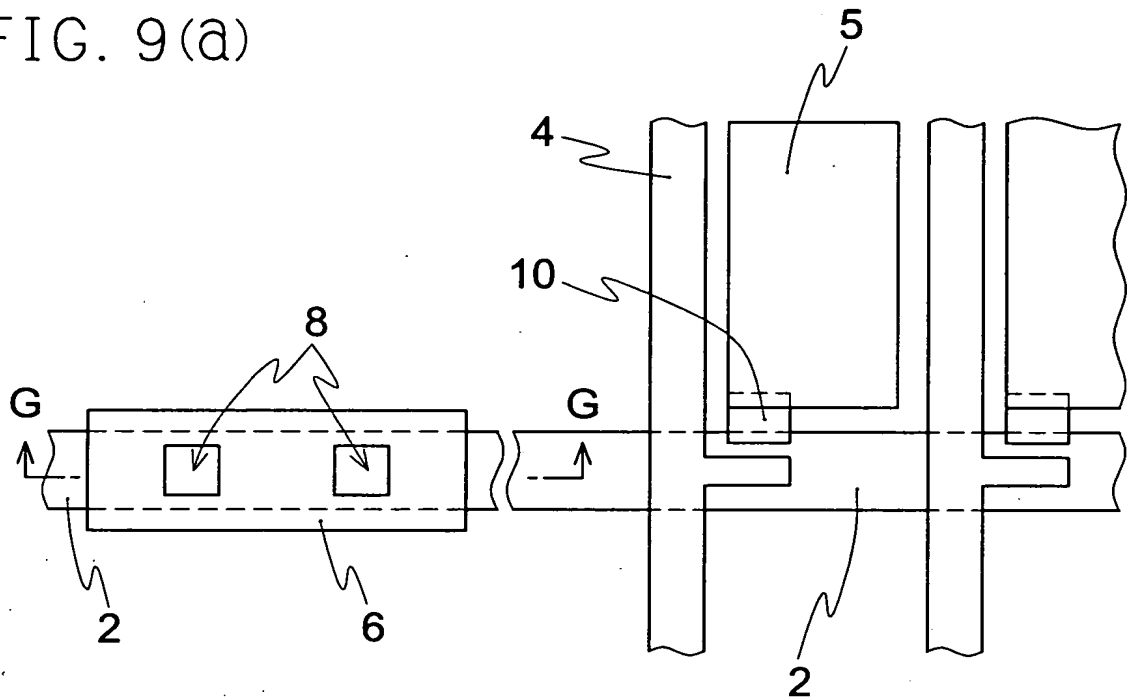
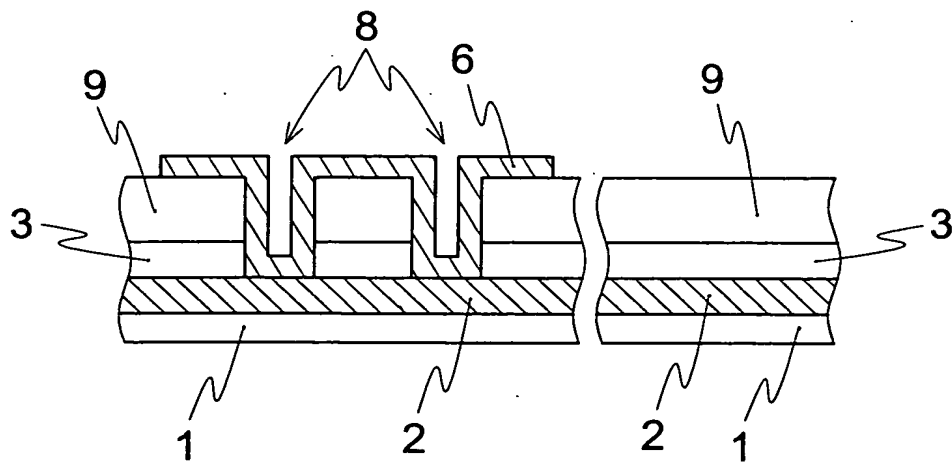


FIG. 9(b)



A detailed cross-sectional diagram of a multi-layered electronic assembly. The base consists of two horizontal layers, labeled 1 and 3. Layer 1 is the bottom-most substrate, while layer 3 is positioned above it. Above layer 3 is a thick, stepped dielectric or insulating layer, labeled 15. On top of layer 15, there are several rectangular blocks or components, some of which are hatched to indicate different materials. These include a large central block labeled 7, and smaller blocks labeled 6, 8, 9, 11, 13, and 15. Arrows point from the labels to their respective parts: label 1 points to the bottom substrate; label 3 points to the layer immediately above it; label 6 points to a small block on the left; label 7 points to the large central block; label 8 points to a hatched block on the right; label 9 points to another hatched block on the far right; label 11 points to a block below the main assembly; label 13 points to a block on the right side; and label 15 points to the thick stepped layer. The entire assembly is shown in a perspective view, highlighting its complex, multi-tiered structure.